

V <sub>DSS</sub>	30V
R <sub>DS(on)</sub> (Max.)	21.4mΩ
I <sub>D</sub>	±9.0A
P <sub>D</sub>	3.0W

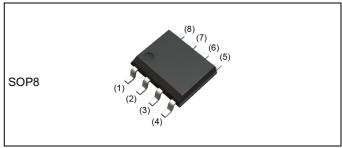
### Features

- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free

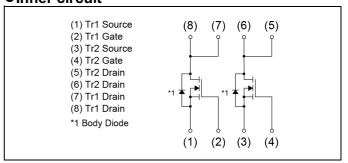
Application

Switching

### Outline



### •Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Type	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	TB1
	Marking	SH8KA4

### ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	30	V
Continuous drain current	I <sub>D</sub> *1	±9.0	Α
Pulsed drain current	I <sub>DP</sub> *2	±18	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	8.0	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	4.6	mJ
	P <sub>D</sub> *1	3.0	
Power dissipation (total)	P <sub>D</sub> *4	2.0	W
	P <sub>D</sub> *5	1.4	
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

### ●Thermal resistance

Parameter	Symbol		Linit		
Faianielei	Symbol	Min.	Тур.	Max.	Unit
Thermal registance innetion, ambient (total)	R <sub>thJA</sub> *4	-	-	62.5	°C/W
Thermal resistance, junction - ambient (total)	R <sub>thJA</sub> *5	-	-	89.2	C/VV

## ● Electrical characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Davanastav	Cy made al	Conditions	Values			Unit	
Parameter	- <b>,</b>		Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	30	-	-	V	
Breakdown voltage	ΔV <sub>(BR)DSS</sub>	I <sub>D</sub> = 1mA		21		mV/°C	
temperature coefficient	$\Delta T_{j}$	referenced to 25°C	-	21	-	IIIV/ C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V		-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 1mA$	1.0	-	2.5	V	
Gate threshold voltage	$\Delta V_{GS(th)}$	I <sub>D</sub> = 1mA		-3		m\//°C	
temperature coefficient	ΔT <sub>j</sub>	referenced to 25°C	-	-3	-	mV/°C	
Static drain - source	D *6	V <sub>GS</sub> = 10V, I <sub>D</sub> = 9.0A	-	16.5	21.4	0	
on - state resistance	R <sub>DS(on)</sub> *6	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 8.0A	-	22.2	28.9	mΩ	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	3.4	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *6	V <sub>DS</sub> = 5V, I <sub>D</sub> = 8.0A	4.6	-	-	S	

<sup>\*1</sup> Pw ≤ 1s, Mounted on a ceramic board (30×30×0.8mm), Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = 15V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a ceramic board (30×30×0.8mm)

<sup>\*5</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*6</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

Darameter	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	640	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15V	-	110	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	90	-	
Turn - on delay time	t <sub>d(on)</sub> *6	V <sub>DD</sub> ≈ 15V,V <sub>GS</sub> = 10V	-	8	-	
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = 4.5A	1	19	-	no
Turn - off delay time	t <sub>d(off)</sub> *6	$R_L = 3.3\Omega$		33	-	ns
Fall time	t <sub>f</sub> *6	$R_G = 10\Omega$	-	7	-	

# ● Gate charge characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Daramatar	Cymah al	Conditions -		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
	$Q_g^{*6}$		V <sub>GS</sub> = 10V	-	15.5	-	
Total gate charge		V <sub>DD</sub> ≃ 15V		-	7.9	-	C
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 9.0A	V <sub>GS</sub> = 4.5V	-	3.1	-	nC
Gate - Drain charge	Q <sub>gd</sub> *6			-	2.8	-	

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

### <Tr1 and Tr2>

Parameter	Symbol	Conditions		Unit		
raianetei	Symbol	Symbol Conditions		Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	1.67	_
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	18	А
Forward voltage	V <sub>SD</sub> *6	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.67A	-	-	1.2	V

Fig.1 Power Dissipation Derating Curve

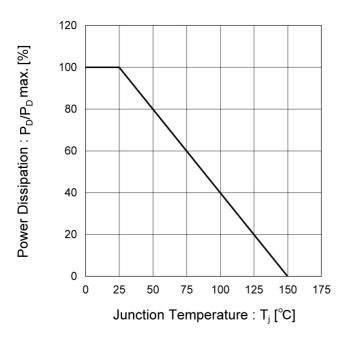
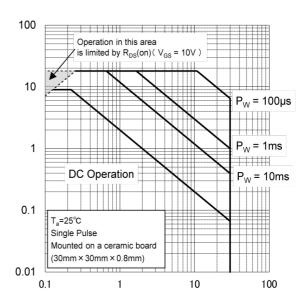


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

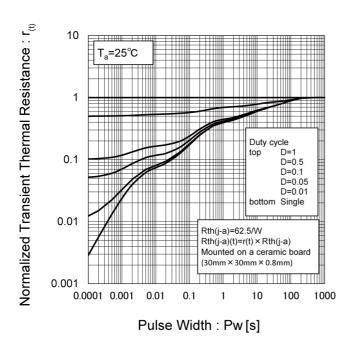
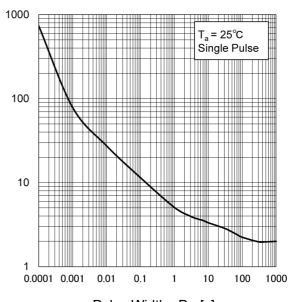


Fig.4 Single Pulse Maximum Power Dissipation



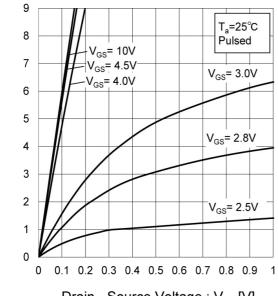
Pulse Width: Pw[s]

Peak Transient Power : P(W)

Drain Current : I<sub>D</sub> [A]

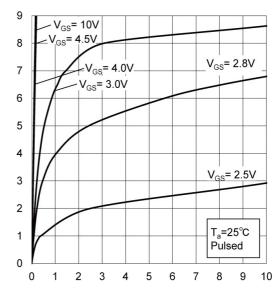
### • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)



 $Drain - Source\ Voltage: V_{DS}[V]$ 

Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

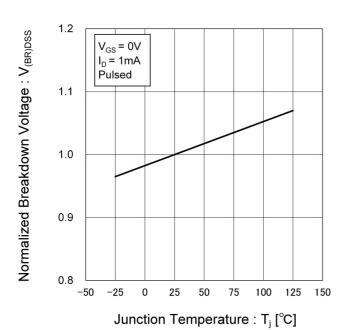


Fig.8 Typical Transfer Characteristics

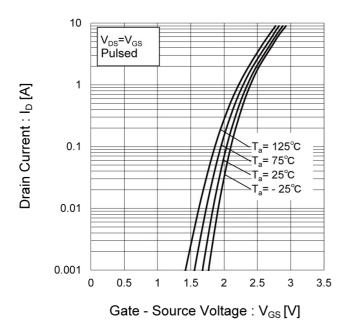
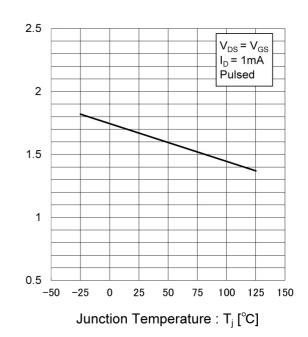


Fig.9 Gate Threshold Voltage vs.
Junction Temperature



Gate Threshold Voltage : V<sub>GS(th)</sub> [V]

Fig.10 Forward Transfer Admittance vs.
Drain Current

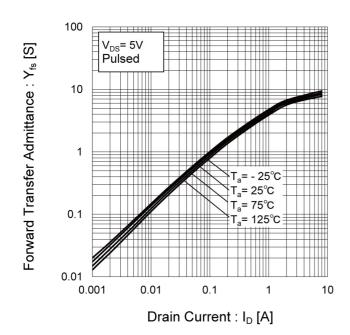


Fig.11 Drain Current Derating Curve

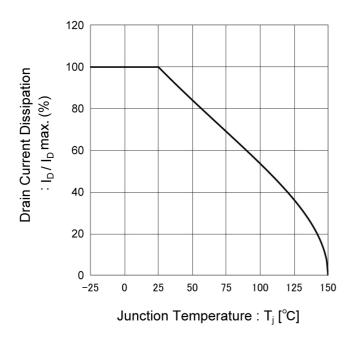


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

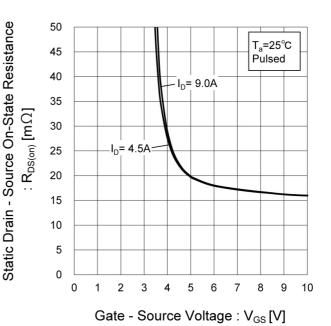
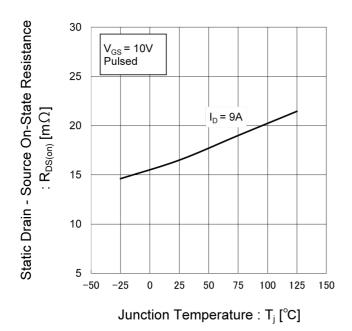


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



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Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

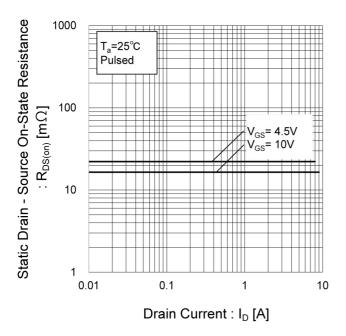


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

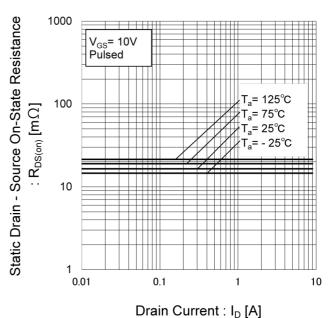


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

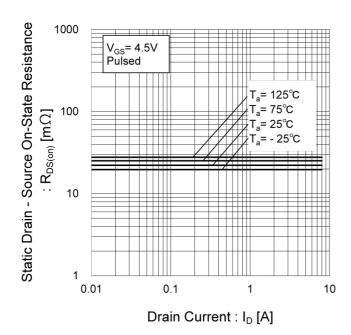


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

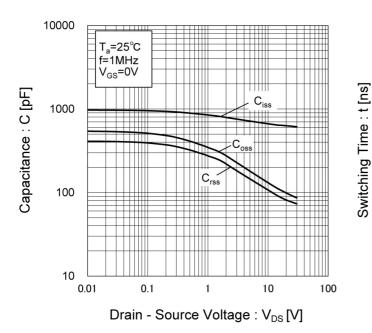


Fig.18 Switching Characteristics

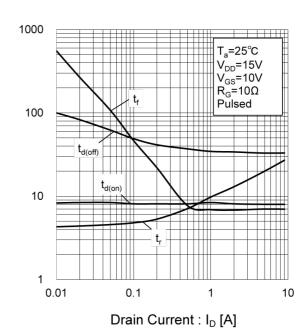


Fig.19 Typical Gate Charge

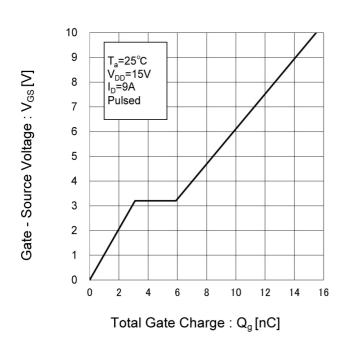
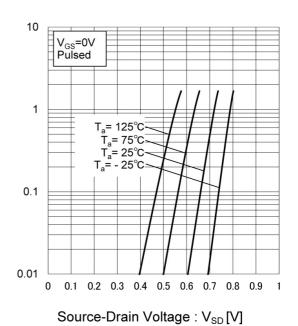


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

### • Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

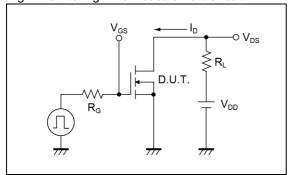


Fig.2-1 Gate Charge Measurement Circuit

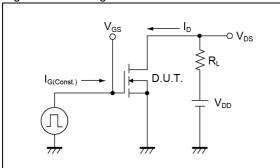


Fig.3-1 Avalanche Measurement Circuit

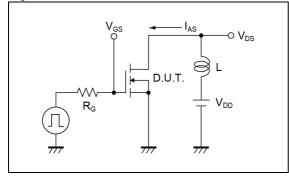


Fig.1-2 Switching Waveforms

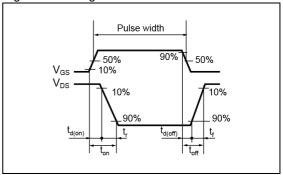


Fig.2-2 Gate Charge Waveform

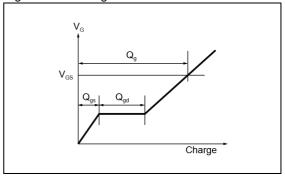
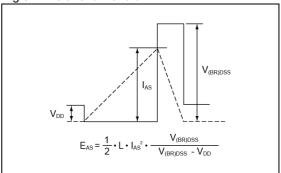


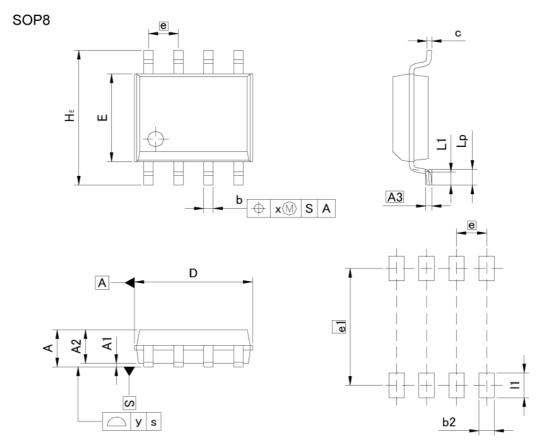
Fig.3-2 Avalanche Waveform



### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

### Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIME	ETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	-	1.75	-	0.069		
A1	0.1	15	0.0	06		
A2	1.40	1.60	0.055	0.063		
A3	0.2	25	0.0	10		
b	0.30	0.50	0.012	0.020		
С	0.10	0.30	0.004	0.012		
D	4.80	5.20	0.189	0.205		
Е	3.75	4.05	0.148	0.159		
е	1.2	27	0.0	50		
HE	5.70	6.30	0.224	0.248		
L1	0.40	0.60	0.016	0.024		
Lp	0.65	0.85	0.026	0.033		
х	0.1	15	0.006			
у	0.1	0.10		0.004		
DIM	MILIME	ETERS	INCI	HES		
DIM	MIN	MAX	MIN	MAX		

0.65

1.15

5.15

Dimension in mm/inches

b2

e 1 11



0.026

0.045

0.203

# **Notice**

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1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CL A C C TT	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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